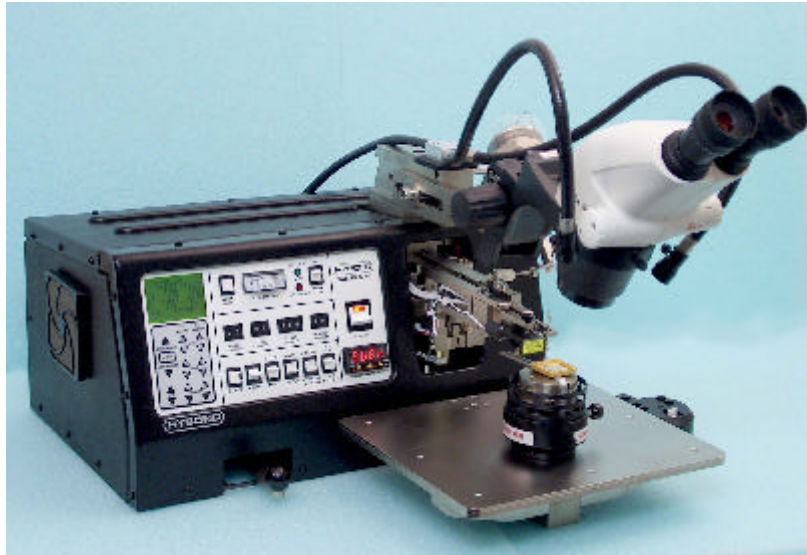


# HYBOND

*Soft Touch™*

## MODEL 626 MULTIPURPOSE DIGITAL THERMOSONIC WIRE BONDER

Ball Bonder, Wedge Bonder, Bump Bonder, Peg Bonder and more.



### STANDARD FEATURES:

- ! Motorized Z control in auto and manual modes (fast & slow speeds for manual).
- ! 100 bond schedules programmable in non-volatile memory.
- ! Selectable/adjustable Reset Heights (Constant or Adaptive).
- ! 1-2-2 auto stitch or manual continuous stitch in manual & auto modes when ball bonding.
- ! Sensor bond actuation for variable bond height bonding.
- ! Audio and visual bond indicators.
- ! Static dissipative enclosure.
- ! 0.740 inch max. vertical bonding window.
- ! Vertical deep access of 0.53 inch when using 0.750 inch Capillary.
- ! Horizontal reach of 6.5 inches.
- ! Programmable loop and search heights.
- ! Built-in digital temperature controller.
- ! High/low power PLL ultrasonic generator.
- ! Swing away wire/ribbon clamps.
- ! 2 inch and 0.5 inch inertial spool holders.
- ! Z control by foot-switches or manipulator.
- ! **Ball, Wedge, Bump or Peg bond capable.**
- ! Electronic ball size control 0-4x wire diam.

Model 626 is a Deep Access, Long Reach Wire Bonder that **can operate as a Ball, Wedge, Bump or Peg bonder**. The 626 can be used for wire diameters from 0.7 to 2.0 mil (18 to 51 $\mu$ m) gold wire when in ball bonder configuration or 0.5 to 3.0 mil (12 to 76 $\mu$ m) and ribbon up to 1.0 x 12.0 mil (25 x 300 $\mu$ m) when in wedge or Peg bonding mode. The 626 was specifically designed for applications that require bonding at extreme height differences between 1<sup>st</sup> and 2<sup>nd</sup> bond and for bonding wires to sensitive devices such as gallium arsenide FET's and LED's. Model 626's motorized wire feed and wire/ribbon clamping system provide superior wire/ribbon control and allow the operator to increase or decrease tail length in 1 mil (25 $\mu$ m) increments at a touch of a switch. 626 shows actual units for set up of bond parameters. Change over from Ball bonder to Wedge bonder requires only a press of a button to turn EFO power to zero and a change from capillary to wedge tool. 626 can also operate in Bump or Peg bonding modes. Add OP-47 for pick, place and bond feature.

### Partial List of Available Options:

- ! OP-06S6: Leica Stereo Zoom Microscope.
- ! OP-06A: Nikon SMZ-660 Microscope.
- ! OP-08A: Dual Fiber Optic Illuminator.
- ! OP-30A: 8:1 X-Y Manipulator.
- ! OP-31: Tool Heater and Temp. Controller.

- ! OP-82: Heated Transducer for Tool Heat.
- ! WST-15A: Heated Work Stage, 2.125 in. Top.
- ! WST-19A: Heated Work Stage, 4 x 6 in. Top.
- ! WST-65: Heated Work Stage, 10 x 6 in. Top.
- ! Wire and Ball tool as ordered per application.

### Specifications for Model 626:

- ! Ultrasonic (U/S) System: PLL self tuning. 62.5KHz (nominal) system ( $\pm 2.5$ KHz).
- ! U/S Power Range: 0-0.2 Watt on low setting and 0-2 Watts on high setting.
- ! Bond Time Range: 0mSec. to 900mSec.
- ! Bond Force Range: 12gr. to 250gr.
- ! Temperature control Range: Ambient to 250 degrees Celsius.
- ! Bondable Wire Diameters: 0.5 to 3.0 mil (12,7 to 75Fm) diameter.
- ! Bondable Ribbon Dimensions: Up to 1x20mil (25,4 x 510Fm) in Wedge bonder mode.
- ! Bondable Wire/Ribbon Materials: Gold (aluminum and gold coated copper for wedge bonder).
- ! Bond head movement: Motorized (servo). Activated by manipulator mounted switches or foot switches.
- ! Bond actuation: By sensor at bond surface contact.
- ! Z Travel/Vertical Bonding Window: 0.750in. (1,90cm)/0.740in. (1,87cm)
- ! Table Motion: 4:1, manual.
- ! Input Power Requirements: 90 - 260VAC 50/60Hz @ 10A max.
- ! Minimum Bench Space Required: 20.0 x 25.0 in. (50,8 x 63,5cm).
- ! Unit Weight/Shipping Weight: 70lbs (31,8Kg)/150lbs (68,2Kg). Shipping weight may vary.
- ! Industry Standards: CE.



For more information, contact:

**BITA ELECTRONIQUE S.A.**, 45 RTE D'ARLON, LU-1140 LUXEMBOURG VILLE, Luxembourg, Ph. +352 450010, Fx. +352 332643, [www.bitalu.lu](http://www.bitalu.lu), [info@bitalu.lu](mailto:info@bitalu.lu)